

MAZPxxxH Series

Silicon planar type

For surge absorption circuits

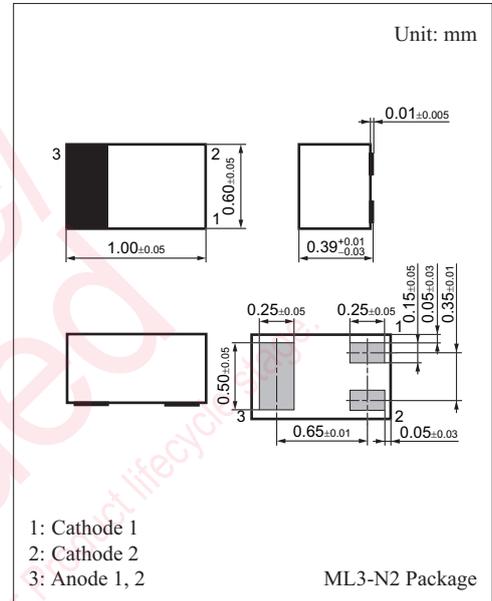
■ Features

- Two elements are contained in one package, optimum for high-density mounting

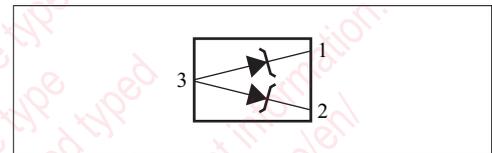
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation *	P_T	200	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $P_T = 200$ mW achieved with a printed circuit board. (2-chips total)



Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

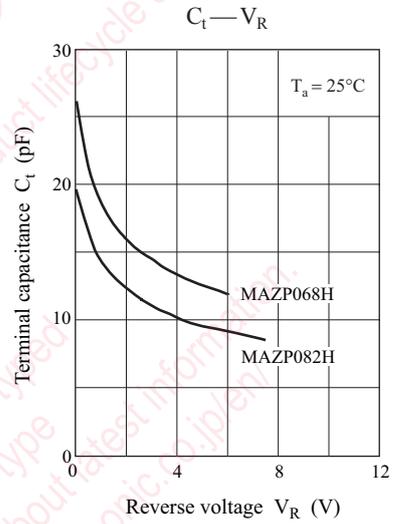
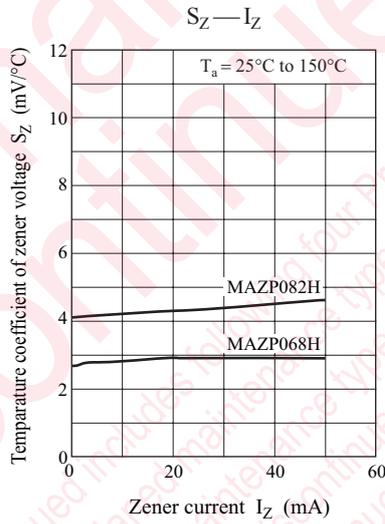
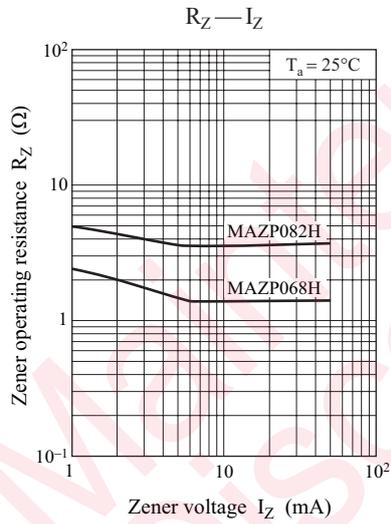
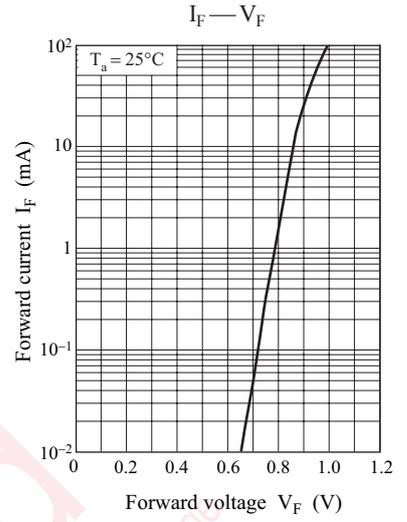
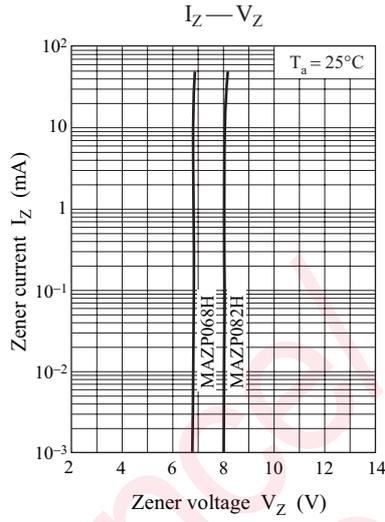
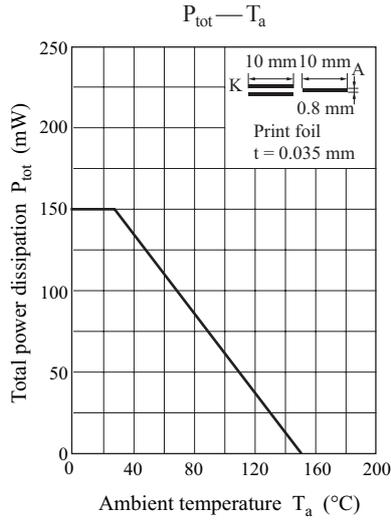
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage *	V_Z	I_Z Specified value				V
Zener rise operating resistance	R_{ZK}	I_Z Specified value	Refer to the list of the electrical characteristics within part numbers			Ω
Zener operating resistance	R_Z	I_Z Specified value				Ω
Reverse current	I_R	V_R Specified value				μA

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Electrostatic breakdown voltage: ± 10 kV
Test method: IEC1000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)
3. The temperature must be controlled 25°C for V_Z measurement.
 V_Z value measured at other temperature must be adjusted to $V_Z (25^\circ\text{C})$
4. *: V_Z guaranteed 20 ms after current flow.

■ Electrical Characteristics within Part Numbers $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Part number	Zener voltage V_Z (V)			Zener rise operating resistance R_{ZK} (Ω)		Zener operating resistance R_Z (Ω)		Reverse current I_R (μA)		Marking symbol	
	I_Z (mA)	Min	Typ	Max	I_Z (mA)	Max	I_Z (mA)	Max	V_R (V)		Max
MAZP068H	5	6.40	6.80	7.20	0.5	60	5	30	4.0	0.1	B6
MAZP082H	5	7.70	8.20	8.70	0.5	60	5	30	5.0	0.1	6



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